



Bluetooth Low Energy Module



BDE-BLEM201P

- Ultra low power consumption: 0.5uA@PowerMode3 (External Interrupts)
- Antenna: PCB antenna
- Size: 16.55mm x10.88mm x 1.5mm (Without Shielding)
16.55mm x10.88mm x 2.2mm (With Shielding)
- BQB certification
- FCC ID: 2ABRUBDLEM201P
- CE 2200 compliant, RoHs compliant

Key Features

- Bluetooth 4.0 single-mode compliant
- Support master and slave modes, 3+ simultaneous connections in master mode
- Integrated Bluetooth Low Energy stack, no external MCU needed
- RF performance
 - TX power: -23dBm to 0dBm
 - RX sensitivity: up to -94dBm
- Communication range: 100m (LOS)
- Ultra low power 8051 microcontroller core
 - 8K RAM with retention
 - 256K in-system-programming flash
 - 23 GPIOs (21x4mA, 2x20mA)
 - 12-bit ADC with eight channels and configurable resolution
 - Data interfaces: I2C x 1, USART x 2
 - Integrate high-performance comparator

Descriptions

BDE-BLEM201P is a Bluetooth 4.0 single-mode compliant Bluetooth low energy module targeted at low power sensors and PC/Phone accessories.

BDE-BLEM201P highly integrates Bluetooth Low Energy radio, stack, profile and applications in a SoC, without the need of using an external MCU. The module also offers flexible hardware interfaces for the sensor application.

It enables ultra low power connectivity and data transfer for the applications that are sensitive to power consumption, size and cost.

Applications

- Medical devices
- Sports and fitness equipments
- Home electronics
- Mobile and PC accessories
- Industry automation



Block Diagram

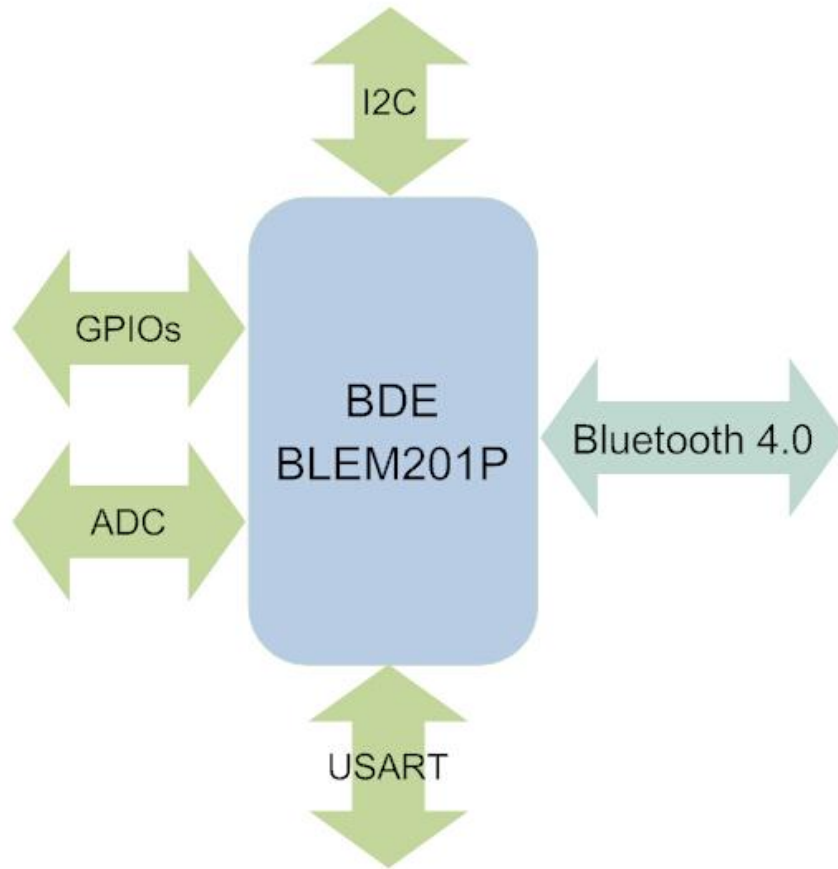


Fig. 1: Block diagram of BDE-BLEM201P

Electrical Characteristics

- Absolute maximum rating

Rating	Min	Typ	Max	Unit
Storage Temperature	-40	-	125	°C
VDD	-0.3	-	3.9	V
Other Terminals	-0.2	-	$VDD+0.3 \leq 3.9$	V

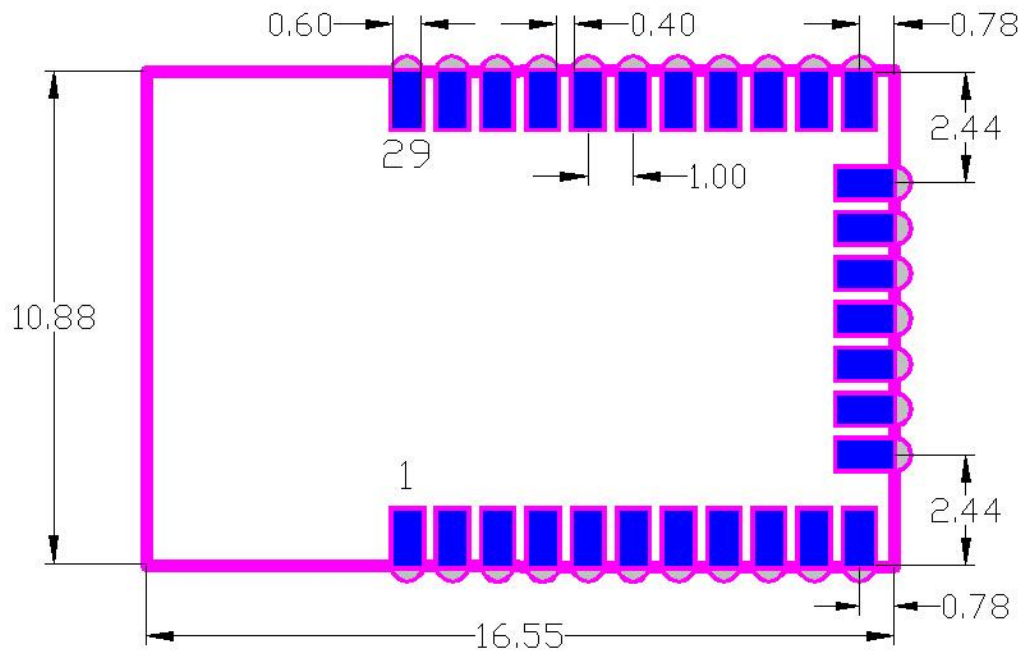


■ Recommended operating conditions

Rating	Min	Typ	Max	Unit
Operating Temperature	-40	-	85	°C
VDD	2	3.3	3.6	V

Overall Dimensions

Fig. 2 shows the overall dimensions of BDE-BLEM201P. The module measures 16.55mm long by 10.88mm wide by 1.5mm high without board level shield.



All Dimensions are in millimeter

Fig. 2: Overall Dimensions of BDE-BLEM201P



Pin Definitions

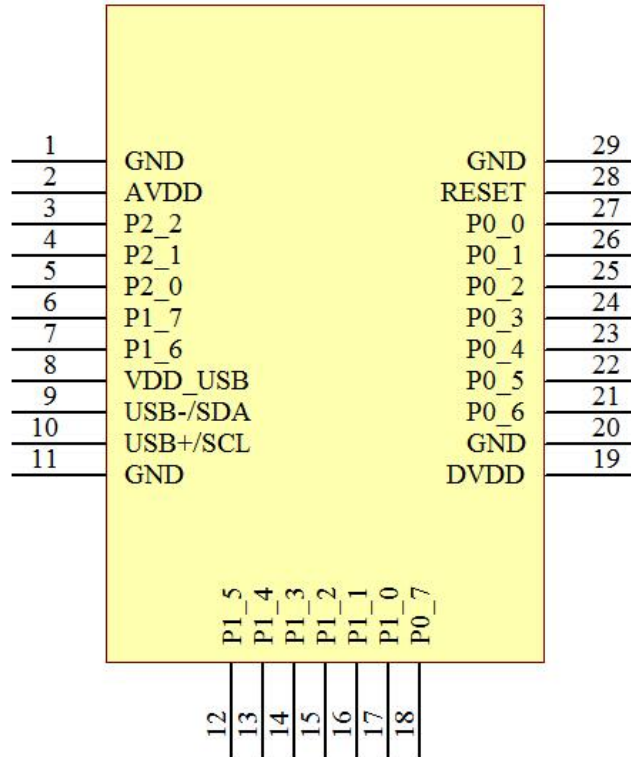


Fig. 3: The pinout of BDE-BLEM201P (TOP)

Table 2: Pin definitions of BDE-BLEM201P

Pin Number	Pin Name	Definitions
1	GND	Power ground
2	AVDD	Power supply for analog circuit
3	P2.2	GPIO
4	P2.1	GPIO
5	P2.0	GPIO
6	P1.7	GPIO
7	P1.6	GPIO
8	NC	NC
9	SDA	Serial clock of I2C
10	SCL	Serial data of I2C
11	GND	Power ground



12	P1.5	GPIO
13	P1.4	GPIO
14	P1.3	GPIO
15	P1.2	GPIO
16	P1.1	GPIO
17	P1.0	GPIO
18	P0.7	GPIO
19	DVDD	Power supply of digital circuit
20	GND	Power ground
21	P0.6	GPIO
22	P0.5	GPIO
23	P0.4	GPIO
24	P0.3	GPIO
25	P0.2	GPIO
26	P0.1	GPIO
27	P0.0	GPIO
28	RESET	Reset pin, active low
29	GND	Power ground
30	RF GND	RF ground
31	RF	Power port
32	RF GND	RF ground

Table 3: Peripheral IO pin mapping

PERIPHERAL / FUNCTION	P0								P1								P2		
	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0	2	1	0
ADC	A7	A6	A5	A4	A3	A2	A1	A0					3						
Operational amplifier						O	-	+											
Analog comparator			+	-															
USART 0 SPI Alt. 2			C	SS	MO	MI					MO	MI	C	SS					
USART 0 UART Alt.2			RT	CT	TX	RX					TX	RX	RT	CT					
USART 1 SPI Alt.2			MI	MO	C	SS				MI	MO	C	SS						
USART 1 UART Alt.2			RX	TX	RT	CT				RX	TX	RT	CT						
TIMER 1 Alt.2		4	3	2	1	0											0	1	2
TIMER 3 Alt.2	3	4											1	0					
TIMER 4 Alt.2									1	0					1	0			
DEBUG																		DC	DD
OBSSSEL											5	4	3	2	1	0			



Module Location

In order to get a fine performance when integrate the module to your product, it is advised to use the recommended module location to the respective PCB.

■ Location in X-Y plane

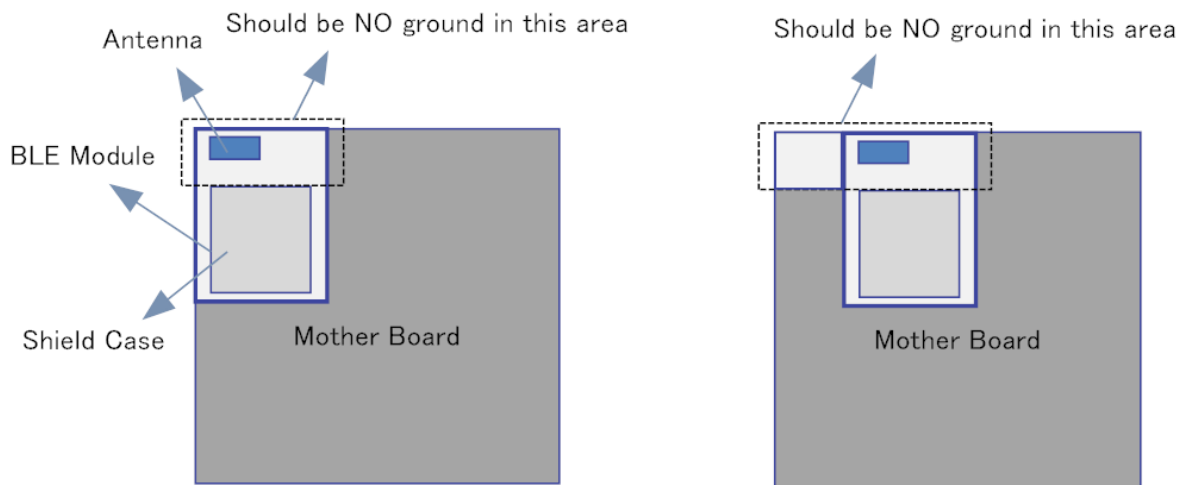


Fig. 4: Recommended location in X-Y plane

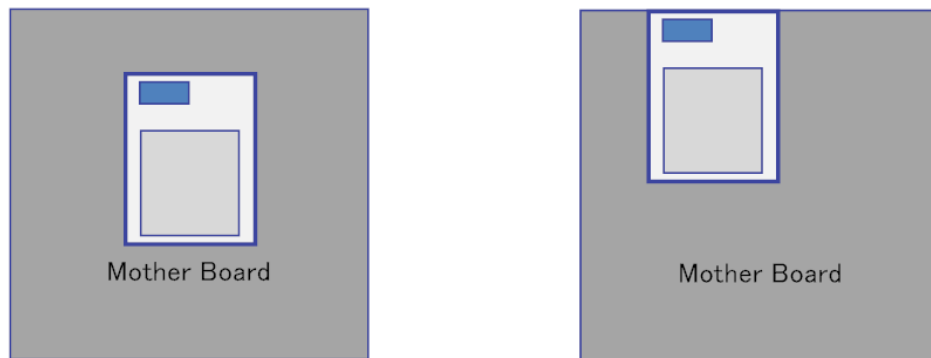


Fig. 5: Not recommended location in X-Y plane



■ Location in Z plane

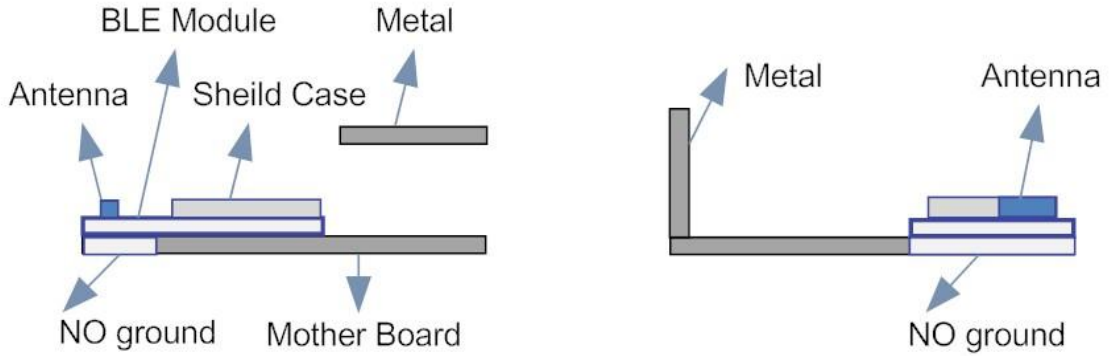


Fig. 6: Recommended location in Z plane

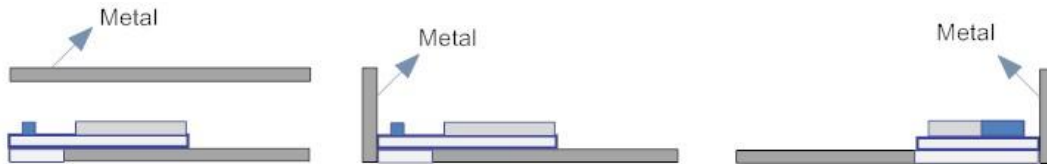


Fig. 7: Not recommended location in Z plane



Typical Solder Reflow Profile

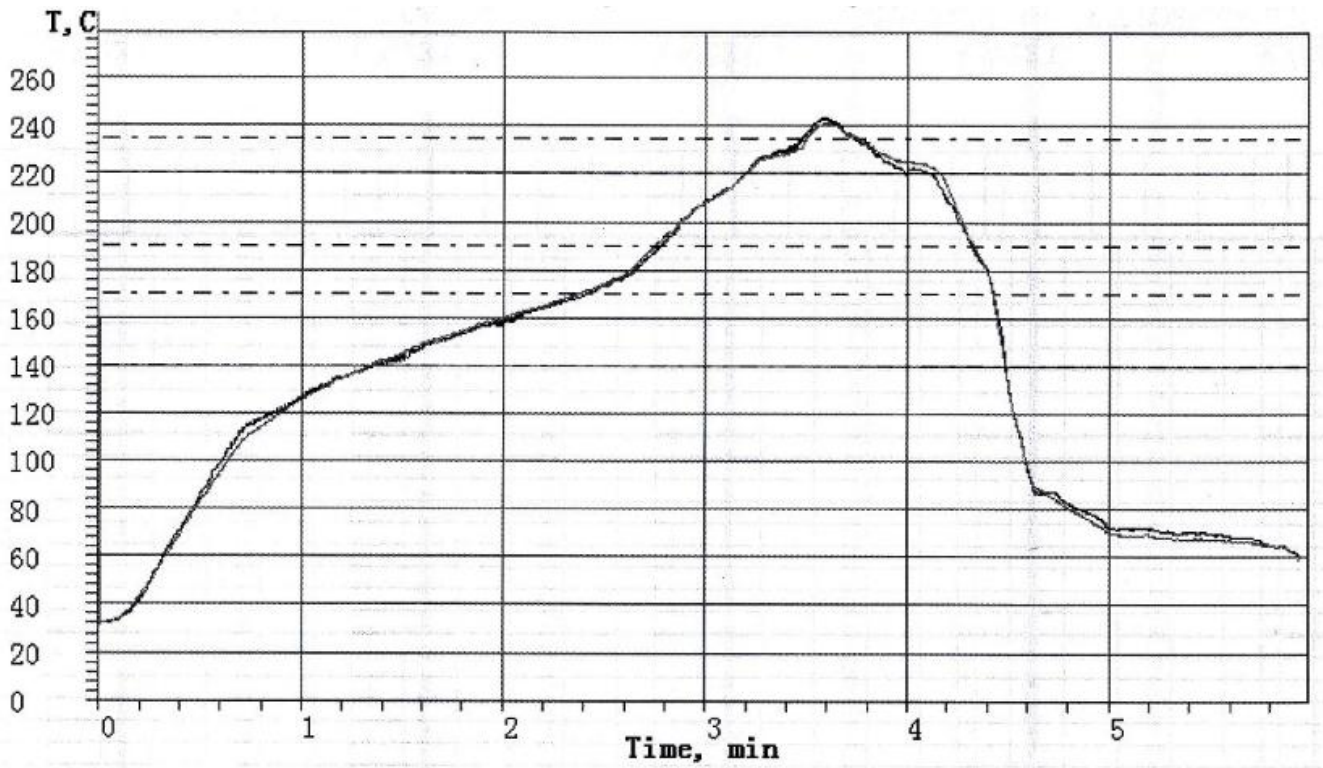


Fig. 8: Typical Solder Reflow Profile



Package Information



Fig. 9: Package information

Contacts

BDE Technology Co. Ltd

Address: Innovation Building C1-1105, 182 Science Ave, Science City, Guangzhou, 510663, China

494 E Thornhill Ln, Palatine, IL 60074, USA

Tel: +86-020-28065335 Fax: +86-020-28065338

Website: www.bdecomm.com Email: info@bdecomm.com

